

74LVC1G175

Single D-type flip-flop with reset; positive-edge trigger

Rev. 01 — 18 October 2004

Product data sheet

1. General description

The 74LVC1G175 is a high-performance, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

The input can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device in a mixed 3.3 V and 5 V environment.

This device is fully specified for partial power-down applications using I_{off} . The I_{off} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

The 74LVC1G175 is a single positive edge triggered D-type flip-flop with individual data (D) input, clock (CP) input, master reset ($\overline{MR}$) input, and Q output.

The master reset ($\overline{MR}$) is an asynchronous active LOW input and operate independently of the clock input. Information on the data input is transferred to the Q output on the LOW-to-HIGH transition of the clock pulse. The D input must be stable one set-up time prior to the LOW-to-HIGH clock transition, for predictable operation.

Schmitt-trigger action at all inputs makes the circuit highly tolerant to slower input rise and fall times.

2. Features

- Wide supply voltage range from 1.65 V to 5.5 V
- 5 V tolerant inputs for interfacing with 5 V logic
- High noise immunity
- Complies with JEDEC standard:
 - ◆ JESD8-7 (1.65 V to 1.95 V)
 - ◆ JESD8-5 (2.3 V to 2.7 V)
 - ◆ JESD8B/JESD36 (2.7 V to 3.6 V).
- ± 24 mA output drive ($V_{CC} = 3.0$ V)
- ESD protection:
 - ◆ HBM EIA/JESD22-A114-B exceeds 2000 V
 - ◆ MM EIA/JESD22-A115-A exceeds 200 V.
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Inputs accept voltages up to 5 V
- Multiple package options
- Specified from -40 °C to $+85$ °C and -40 °C to $+125$ °C.

PHILIPS

3. Quick reference data

Table 1: Quick reference data
GND = 0 V; T_{amb} = 25 °C; t_r = t_f ≤ 2.5 ns.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t _{PHL} , t _{PLH}	propagation delay CP to Q	C _L = 50 pF; V _{CC} = 3.3 V	1.0	3.1	5.7	ns
	propagation delay MR to Q	C _L = 50 pF; V _{CC} = 3.3 V	1.0	2.5	5.8	ns
f _{max}	maximum clock frequency	C _L = 50 pF; V _{CC} = 3.3 V	175	300	-	MHz
C _I	input capacitance		-	2.5	-	pF
C _{PD}	power dissipation capacitance	V _{CC} = 3.3 V	[1] [2] -	14	-	pF

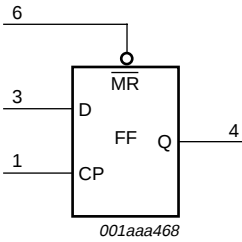
- [1] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
P_D = C_{PD} × V_{CC}² × f_i × N + Σ(C_L × V_{CC}² × f_o) where:
f_i = input frequency in MHz;
f_o = output frequency in MHz;
C_L = output load capacitance in pF;
V_{CC} = supply voltage in Volts;
N = number of inputs switching;
Σ(C_L × V_{CC}² × f_o) = sum of the outputs.
- [2] The condition is V_i = GND to V_{CC}.

4. Ordering information

Table 2: Ordering information

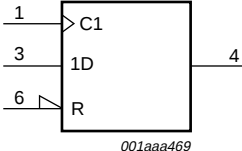
Type number	Package			
	Temperature range	Name	Description	Version
74LVC1G175GW	−40 °C to +125 °C	SC-88	plastic surface mounted package; 6 leads	SOT363
74LVC1G175GV	−40 °C to +125 °C	SC-74	plastic surface mounted package; 6 leads	SOT457
74LVC1G175GM	−40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886

5. Functional diagram



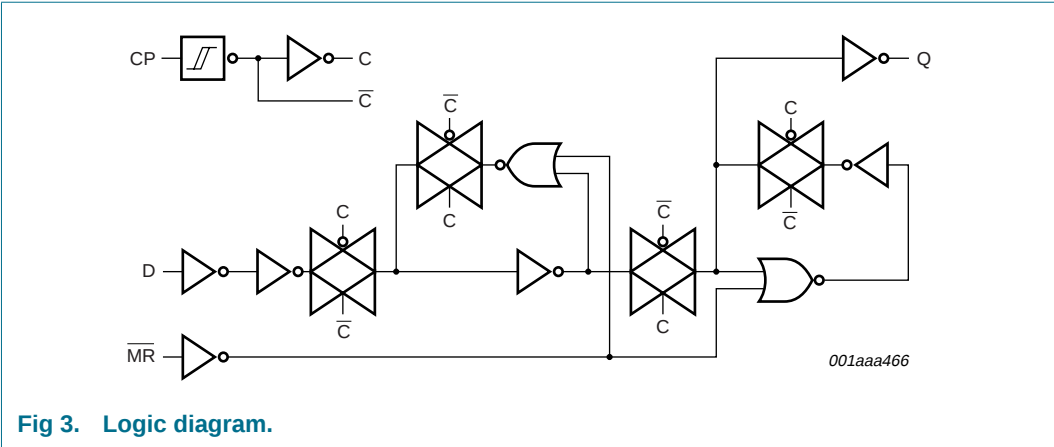
The logic symbol for the 74LVC1G175 is a rectangular block labeled 'FF' (flip-flop). It has four inputs: 'MR' (Master Reset) at the top, 'D' (Data) on the left, 'CP' (Clock Pulse) at the bottom left, and 'Q' (Output) on the right. The inputs are numbered 6, 3, 1, and 4 respectively. The output is labeled 'Q' and is connected to pin 4. The symbol is identified by the number '001aaa468' at the bottom.

Fig 1. Logic symbol.



The IEC logic symbol for the 74LVC1G175 is a rectangular block. It has three inputs: 'C1' (Clock) at the top left, '1D' (Data) on the left, and 'R' (Reset) at the bottom left. The inputs are numbered 1, 3, and 6 respectively. The output is labeled '4' on the right. The symbol is identified by the number '001aaa469' at the bottom.

Fig 2. IEC logic symbol.



6. Pinning information

6.1 Pinning

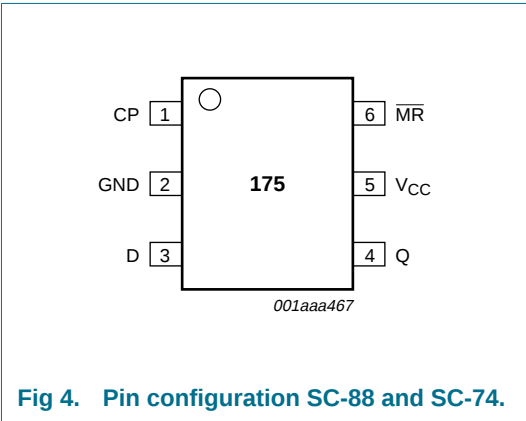


Fig 4. Pin configuration SC-88 and SC-74.

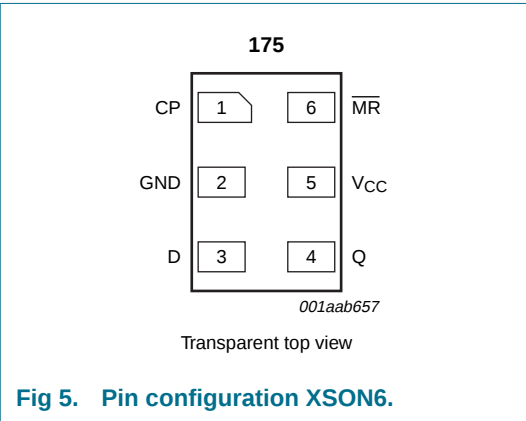


Fig 5. Pin configuration XSON6.

6.2 Pin description

Table 3: Pin description

Symbol	Pin	Description
CP	1	clock input (LOW-to-HIGH, edge-triggered)
GND	2	ground (0 V)
D	3	data input
Q	4	flip-flop output
V _{CC}	5	supply voltage
MR	6	master reset input (active LOW)

7. Functional description

7.1 Function table

Table 4: Function table ^[1]

Operating mode	Input			Output
	MR	CP	D	Q
Reset (clear)	L	X	X	L
Load '1'	H	↑	h	H
Load '0'	H	↑	l	L

- [1] H = HIGH voltage level;
 h = HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition;
 L = LOW voltage level;
 l = LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition;
 ↑ = LOW-to-HIGH CP transition;
 X = don't care.

8. Limiting values

Table 5: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+6.5	V
I_{IK}	input diode current	$V_I < 0$ V	-	-50	mA
V_I	input voltage		^[1] -0.5	+6.5	V
I_{OK}	output diode current	$V_O > V_{CC}$ or $V_O < 0$ V	-	±50	mA
V_O	output voltage	active mode	^{[1] [2]} -0.5	$V_{CC} + 0.5$	V
		Power-down mode	^{[1] [2]} -0.5	+6.5	V
I_O	output diode current	$V_O = 0$ V to V_{CC}	-	±50	mA
I_{CC}, I_{GND}	V_{CC} or GND current		-	±100	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	power dissipation	$T_{amb} = -40$ °C to +125 °C	-	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] When $V_{CC} = 0$ V (Power-down mode), the output voltage can be 5.5 V in normal operation.

9. Recommended operating conditions

Table 6: Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		1.65	5.5	V
V_I	input voltage		0	5.5	V
V_O	output voltage	active mode	0	V_{CC}	V
		Power-down mode; $V_{CC} = 0$ V	0	5.5	V

Table 6: Recommended operating conditions ...continued

Symbol	Parameter	Conditions	Min	Max	Unit
T_{amb}	ambient temperature		-40	+125	°C
t_r, t_f	input rise and fall times	$V_{CC} = 1.65 \text{ V to } 2.7 \text{ V}$	0	20	ns/V
		$V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$	0	10	ns/V

10. Static characteristics

Table 7: Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{amb} = -40 \text{ °C to } +85 \text{ °C}$ [1]						
V_{IH}	HIGH-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7	-	-	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2.0	-	-	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$0.7 \times V_{CC}$	-	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	-	-	0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	-	-	0.8	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	-	$0.3 \times V_{CC}$	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$				
		$I_O = -100 \text{ } \mu\text{A}; V_{CC} = 1.65 \text{ V to } 5.5 \text{ V}$	$V_{CC} - 0.1$	-	-	V
		$I_O = -4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.2	1.54	-	V
		$I_O = -8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.9	2.15	-	V
		$I_O = -12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	2.2	2.50	-	V
		$I_O = -24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.3	2.62	-	V
		$I_O = -32 \text{ mA}; V_{CC} = 4.5 \text{ V}$	3.8	4.11	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$				
		$I_O = 100 \text{ } \mu\text{A}; V_{CC} = 1.65 \text{ V to } 5.5 \text{ V}$	-	-	0.10	V
		$I_O = 4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	-	0.07	0.45	V
		$I_O = 8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	0.12	0.30	V
		$I_O = 12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	-	0.17	0.40	V
		$I_O = 24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	0.33	0.55	V
		$I_O = 32 \text{ mA}; V_{CC} = 4.5 \text{ V}$	-	0.39	0.55	V
I_{LI}	input leakage current	$V_I = 5.5 \text{ V or GND}; V_{CC} = 5.5 \text{ V}$	-	± 0.1	± 5	μA
I_{off}	power OFF leakage current	$V_I \text{ or } V_O = 5.5 \text{ V}; V_{CC} = 0 \text{ V}$	-	± 0.1	± 10	μA
I_{CC}	quiescent supply current	$V_I = V_{CC} \text{ or GND}; I_O = 0 \text{ A}; V_{CC} = 5.5 \text{ V}$	-	0.1	10	μA
ΔI_{CC}	additional quiescent supply current per pin	$V_I = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A}; V_{CC} = 2.3 \text{ V to } 5.5 \text{ V}$	-	5	500	μA
C_I	input capacitance		-	2.5	-	pF

Table 7: Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +125 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.7	-	-	V
		V _{CC} = 2.7 V to 3.6 V	2.0	-	-	V
		V _{CC} = 4.5 V to 5.5 V	0.7 × V _{CC}	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 1.65 V to 1.95 V	-	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 2.7 V to 3.6 V	-	-	0.8	V
		V _{CC} = 4.5 V to 5.5 V	-	-	0.3 × V _{CC}	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = -100 µA; V _{CC} = 1.65 V to 5.5 V	V _{CC} - 0.1	-	-	V
		I _O = -4 mA; V _{CC} = 1.65 V	0.95	-	-	V
		I _O = -8 mA; V _{CC} = 2.3 V	1.7	-	-	V
		I _O = -12 mA; V _{CC} = 2.7 V	1.9	-	-	V
		I _O = -24 mA; V _{CC} = 3.0 V	2.0	-	-	V
		I _O = -32 mA; V _{CC} = 4.5 V	3.4	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = 100 µA; V _{CC} = 1.65 V to 5.5 V	-	-	0.10	V
		I _O = 4 mA; V _{CC} = 1.65 V	-	-	0.70	V
		I _O = 8 mA; V _{CC} = 2.3 V	-	-	0.45	V
		I _O = 12 mA; V _{CC} = 2.7 V	-	-	0.60	V
		I _O = 24 mA; V _{CC} = 3.0 V	-	-	0.80	V
		I _O = 32 mA; V _{CC} = 4.5 V	-	-	0.80	V
I _{LI}	input leakage current	V _I = 5.5 V or GND; V _{CC} = 5.5 V	-	-	±20	µA
I _{off}	power OFF leakage current	V _I or V _O = 5.5 V; V _{CC} = 0 V	-	-	±20	µA
I _{CC}	quiescent supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	40	µA
ΔI _{CC}	additional quiescent supply current per pin	V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 2.3 V to 5.5 V	-	-	5000	µA

[1] All typical values are measured at T_{amb} = 25 °C.

11. Dynamic characteristics

Table 8: Dynamic characteristics

$GND = 0\text{ V}$; see [Figure 8](#)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{amb} = -40\text{ °C to }+85\text{ °C}$ [1]						
t_{PHL}, t_{PLH}	propagation delay CP to Q	see Figure 6				
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	1.5	4.9	13.4	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.0	3.1	7.1	ns
		$V_{CC} = 2.7\text{ V}$	1.0	3.2	7.1	ns
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$ [2]	1.0	3.1	5.7	ns
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	1.0	2.2	4.0	ns
	propagation delay $\overline{MR}$ to Q	see Figure 7				
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	1.5	4.3	12.9	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.0	2.8	7.0	ns
		$V_{CC} = 2.7\text{ V}$	1.0	3.0	7.0	ns
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$ [2]	1.0	2.5	5.8	ns
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	1.0	2.0	4.1	ns
t_W	clock pulse width HIGH or LOW	see Figure 6				
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	6.2	-	-	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	2.7	-	-	ns
		$V_{CC} = 2.7\text{ V}$	2.7	-	-	ns
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$ [2]	2.7	1.3	-	ns
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	2.0	-	-	ns
	master reset pulse width LOW	see Figure 7				
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	6.2	-	-	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	2.7	-	-	ns
		$V_{CC} = 2.7\text{ V}$	2.7	-	-	ns
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$ [2]	2.7	1.6	-	ns
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	2.0	-	-	ns
	removal time master reset	see Figure 7				
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	1.9	-	-	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.4	-	-	ns
		$V_{CC} = 2.7\text{ V}$	1.3	-	-	ns
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$ [2]	1.2	0.4	-	ns
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	1.0	-	-	ns
t_{su}	set-up time D to CP	see Figure 6				
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	2.9	-	-	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7	-	-	ns
		$V_{CC} = 2.7\text{ V}$	1.7	-	-	ns
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$ [2]	1.3	0.5	-	ns
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	1.1	-	-	ns

Table 8: Dynamic characteristics ...continued

GND = 0 V; see [Figure 8](#)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_h	hold time D to CP	see Figure 6				
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.0	-	-	ns
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	0.3	-	-	ns
		$V_{CC} = 2.7 \text{ V}$	0.5	-	-	ns
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	[2] 1.2	0.2	-	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	0.5	-	-	ns
f_{max}	maximum clock pulse frequency	see Figure 6				
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	80	125	-	MHz
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	175	-	-	MHz
		$V_{CC} = 2.7 \text{ V}$	175	-	-	MHz
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	[2] 175	300	-	MHz
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	200	-	-	MHz
C_{PD}	power dissipation capacitance	$V_{CC} = 3.3 \text{ V}$	[3] [4] -	14	-	pF
$T_{amb} = -40 \text{ }^{\circ}\text{C to } +125 \text{ }^{\circ}\text{C}$						
t_{PHL}, t_{PLH}	propagation delay CP to Q	see Figure 6				
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	1.5	-	17	ns
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.0	-	9.0	ns
		$V_{CC} = 2.7 \text{ V}$	1.0	-	9.0	ns
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	0.5	-	7.5	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	0.5	-	5.5	ns
	propagation delay $\overline{\text{MR}}$ to Q	see Figure 7				
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	1.5	-	17	ns
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.0	-	9.0	ns
		$V_{CC} = 2.7 \text{ V}$	1.0	-	9.0	ns
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	0.5	-	7.5	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	0.5	-	5.5	ns
t_w	clock pulse width HIGH or LOW	see Figure 6				
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	6.2	-	-	ns
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	2.7	-	-	ns
		$V_{CC} = 2.7 \text{ V}$	2.7	-	-	ns
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	2.7	-	-	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2.0	-	-	ns
	master reset pulse width LOW	see Figure 7				
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	6.2	-	-	ns
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	2.7	-	-	ns
		$V_{CC} = 2.7 \text{ V}$	2.7	-	-	ns
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	2.7	-	-	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2.0	-	-	ns

Table 8: Dynamic characteristics ...continued

GND = 0 V; see [Figure 8](#)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_{rem}	removal time master reset	see Figure 7				
		$V_{\text{CC}} = 1.65 \text{ V to } 1.95 \text{ V}$	1.9	-	-	ns
		$V_{\text{CC}} = 2.3 \text{ V to } 2.7 \text{ V}$	1.4	-	-	ns
		$V_{\text{CC}} = 2.7 \text{ V}$	1.3	-	-	ns
		$V_{\text{CC}} = 3.0 \text{ V to } 3.6 \text{ V}$	1.2	-	-	ns
		$V_{\text{CC}} = 4.5 \text{ V to } 5.5 \text{ V}$	1.0	-	-	ns
t_{su}	set-up time D to CP	see Figure 6				
		$V_{\text{CC}} = 1.65 \text{ V to } 1.95 \text{ V}$	2.9	-	-	ns
		$V_{\text{CC}} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7	-	-	ns
		$V_{\text{CC}} = 2.7 \text{ V}$	1.7	-	-	ns
		$V_{\text{CC}} = 3.0 \text{ V to } 3.6 \text{ V}$	1.3	-	-	ns
		$V_{\text{CC}} = 4.5 \text{ V to } 5.5 \text{ V}$	1.1	-	-	ns
t_{h}	hold time D to CP	see Figure 6				
		$V_{\text{CC}} = 1.65 \text{ V to } 1.95 \text{ V}$	0.0	-	-	ns
		$V_{\text{CC}} = 2.3 \text{ V to } 2.7 \text{ V}$	0.3	-	-	ns
		$V_{\text{CC}} = 2.7 \text{ V}$	0.5	-	-	ns
		$V_{\text{CC}} = 3.0 \text{ V to } 3.6 \text{ V}$	1.2	-	-	ns
		$V_{\text{CC}} = 4.5 \text{ V to } 5.5 \text{ V}$	0.5	-	-	ns
f_{max}	maximum clock pulse frequency	see Figure 6				
		$V_{\text{CC}} = 1.65 \text{ V to } 1.95 \text{ V}$	80	-	-	MHz
		$V_{\text{CC}} = 2.3 \text{ V to } 2.7 \text{ V}$	175	-	-	MHz
		$V_{\text{CC}} = 2.7 \text{ V}$	175	-	-	MHz
		$V_{\text{CC}} = 3.0 \text{ V to } 3.6 \text{ V}$	175	-	-	MHz
		$V_{\text{CC}} = 4.5 \text{ V to } 5.5 \text{ V}$	200	-	-	MHz

- [1] All typical values are measured at $T_{\text{amb}} = 25 \text{ }^{\circ}\text{C}$.
- [2] These typical values are measured at $V_{\text{CC}} = 3.3 \text{ V}$.
- [3] C_{PD} is used to determine the dynamic power dissipation (P_{D} in μW).
 $P_{\text{D}} = C_{\text{PD}} \times V_{\text{CC}}^2 \times f_{\text{i}} \times N + \Sigma(C_{\text{L}} \times V_{\text{CC}}^2 \times f_{\text{o}})$ where:
 f_{i} = input frequency in MHz;
 f_{o} = output frequency in MHz;
 C_{L} = output load capacitance in pF;
 V_{CC} = supply voltage in Volts;
 N = number of inputs switching;
 $\Sigma(C_{\text{L}} \times V_{\text{CC}}^2 \times f_{\text{o}})$ = sum of the outputs.
- [4] The condition is $V_{\text{I}} = \text{GND to } V_{\text{CC}}$.

12. Waveforms

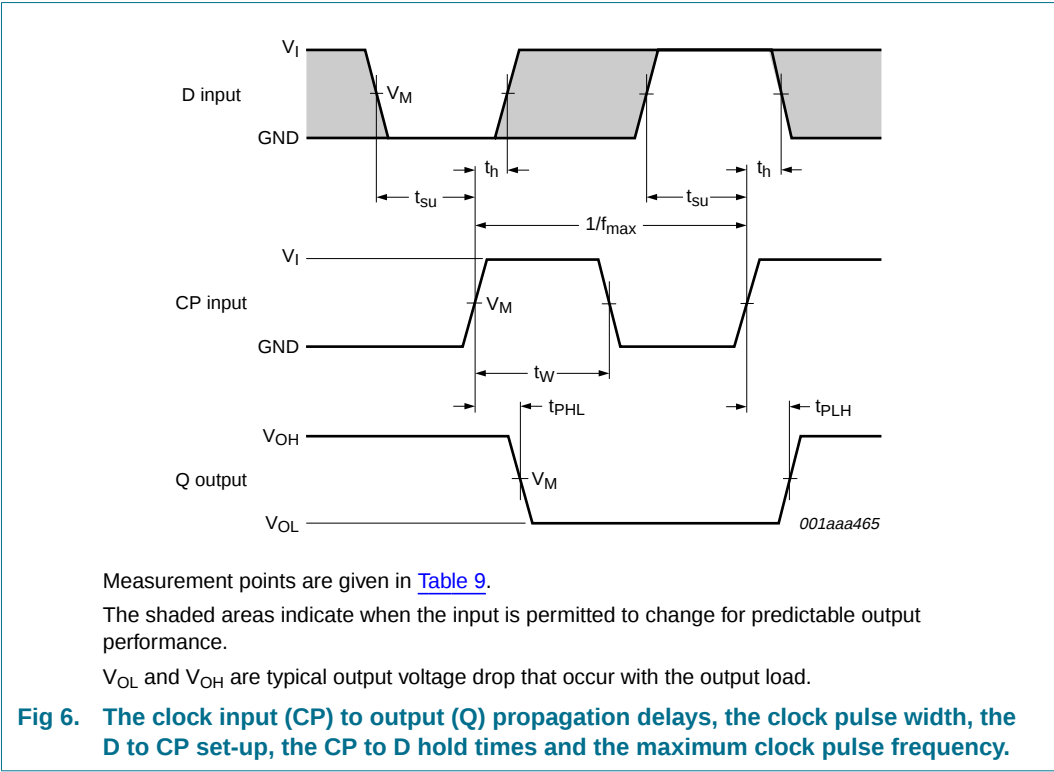


Table 9: Measurement points

Supply voltage	Output	Input		
V_{CC}	V_M	V_M	V_I	$t_r = t_f$
1.65 V to 1.95 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{CC}	≤ 2.0 ns
2.3 V to 2.7 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{CC}	≤ 2.0 ns
2.7 V	1.5 V	1.5 V	2.7 V	≤ 2.5 ns
3.0 V to 3.6 V	1.5 V	1.5 V	2.7 V	≤ 2.5 ns
4.5 V to 5.5 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{CC}	≤ 2.5 ns

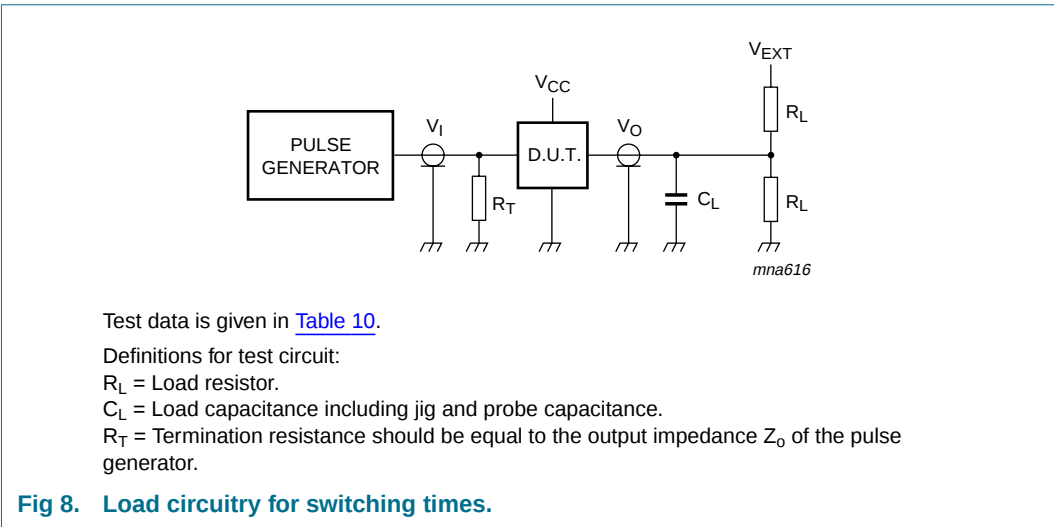
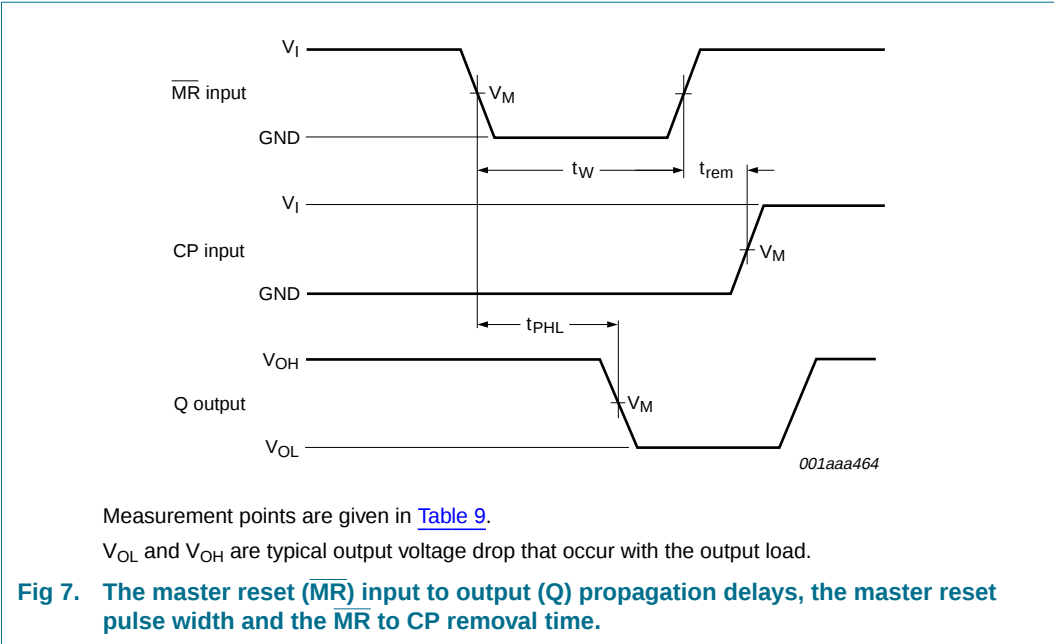


Table 10: Test data

Supply voltage	Input	Load		V_{EXT}		
V_{CC}	V_I	C_L	R_L	t_{PLH} , t_{PHL}	t_{PZH} , t_{PHZ}	t_{PZL} , t_{PLZ}
1.65 V to 1.95 V	V_{CC}	30 pF	1 k Ω	open	GND	$2 \times V_{CC}$
2.3 V to 2.7 V	V_{CC}	30 pF	500 Ω	open	GND	$2 \times V_{CC}$
2.7 V	2.7 V	50 pF	500 Ω	open	GND	6 V
3.0 V to 3.6 V	2.7 V	50 pF	500 Ω	open	GND	6 V
4.5 V to 5.5 V	V_{CC}	50 pF	500 Ω	open	GND	$2 \times V_{CC}$

13. Package outline

Plastic surface mounted package; 6 leads

SOT363

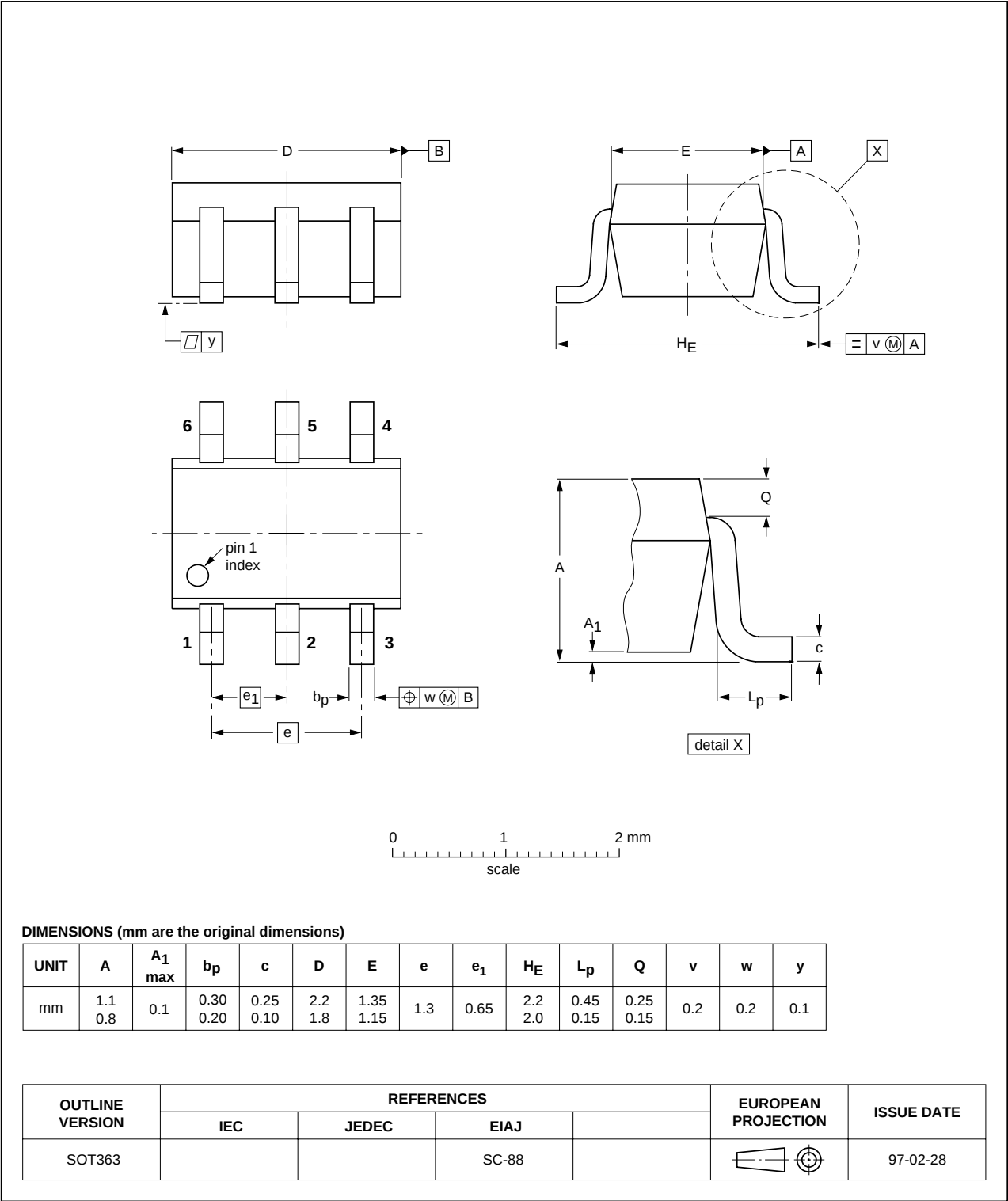


Fig 9. Package outline SOT363 (SC-88).

Plastic surface mounted package; 6 leads

SOT457

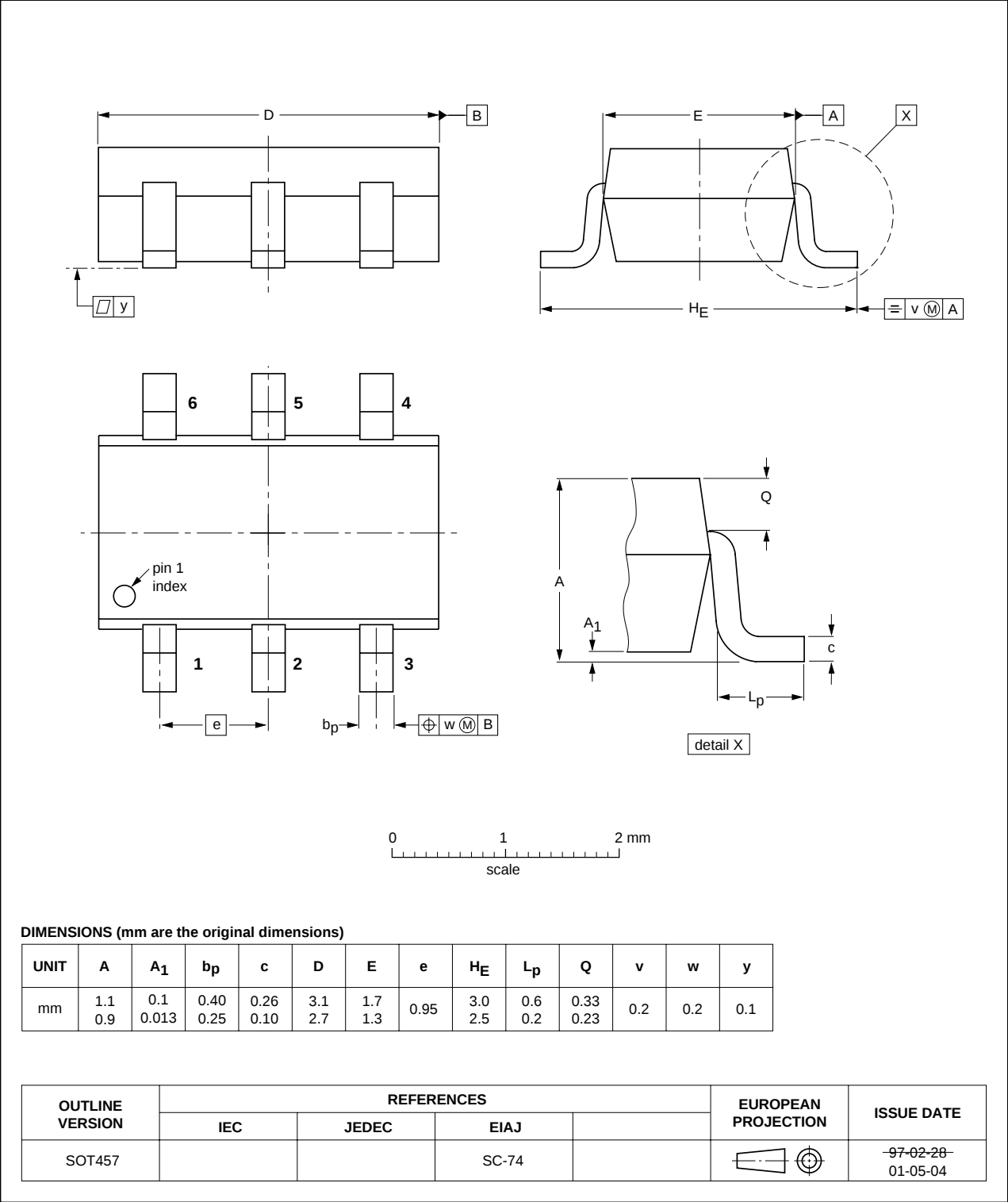
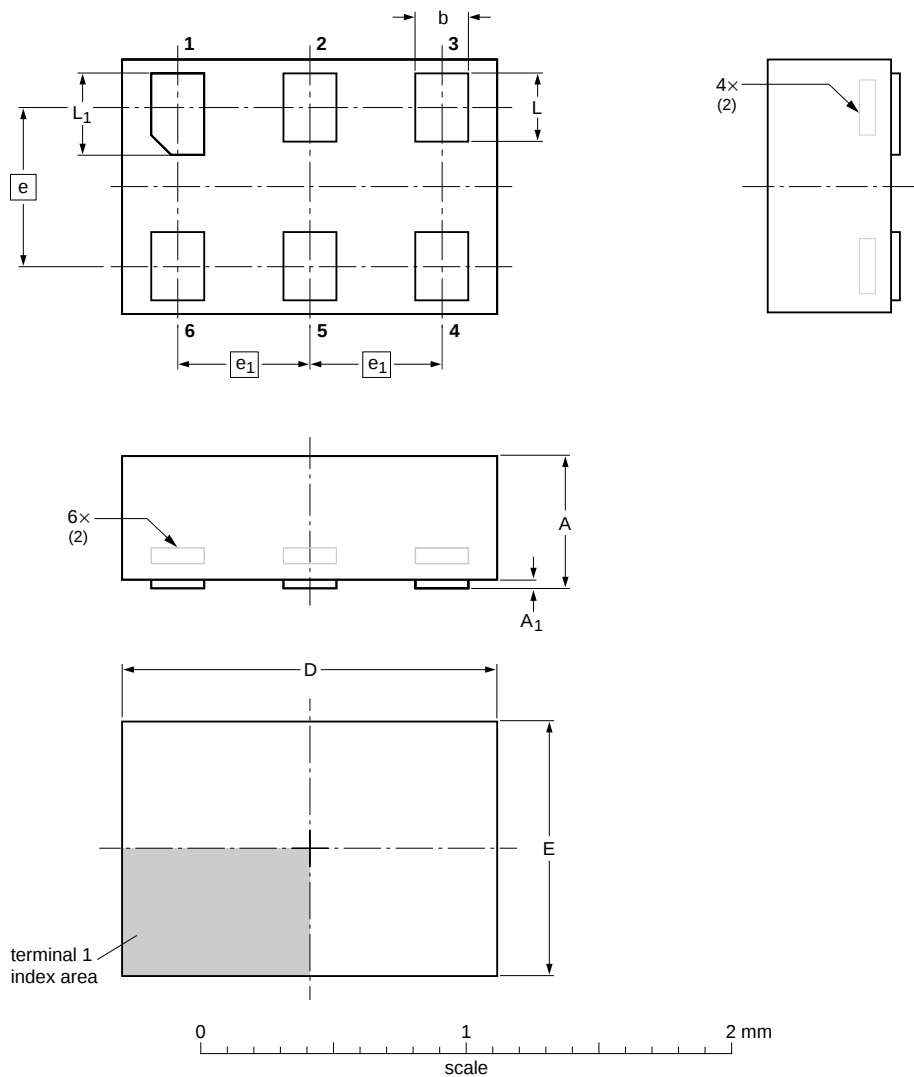


Fig 10. Package outline SOT457 (SC-74).

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886



DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max	A ₁ max	b	D	E	e	e ₁	L	L ₁
mm	0.5	0.04	0.25 0.17	1.5 1.4	1.05 0.95	0.6	0.5	0.35 0.27	0.40 0.32

- Notes
- 1. Including plating thickness.
 - 2. Can be visible in some manufacturing processes.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT886		MO-252				04-07-15 04-07-22

Fig 11. Package outline SOT886 (XSON6).



14. Revision history

Table 11: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
74LVC1G175_2	20041018	Product data sheet	-	9397 750 13762	74LVC1G175_1
Modifications	• Package outline. Marking code and ESD data added.				
74LVC1G175_1	20040318	Product data sheet	-	9397 750 12973	-

15. Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

16. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

17. Disclaimers

Life support — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes in the products - including circuits, standard cells, and/or software - described or contained herein in order to improve design and/or performance. When the product is in full production (status 'Production'), relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN). Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

18. Contact information

For additional information, please visit: <http://www.semiconductors.philips.com>

For sales office addresses, send an email to: sales.addresses@www.semiconductors.philips.com



19. Contents

1 General description 1

2 Features 1

3 Quick reference data 2

4 Ordering information 2

5 Functional diagram 2

6 Pinning information 3

6.1 Pinning 3

6.2 Pin description 3

7 Functional description 4

7.1 Function table 4

8 Limiting values 4

9 Recommended operating conditions 4

10 Static characteristics 5

11 Dynamic characteristics 7

12 Waveforms 10

13 Package outline 12

14 Revision history 15

15 Data sheet status 16

16 Definitions 16

17 Disclaimers 16

18 Contact information 16



© Koninklijke Philips Electronics N.V. 2004

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Date of release: 18 October 2004
Document number: 9397 750 13762

Published in The Netherlands